



Semiconductor training

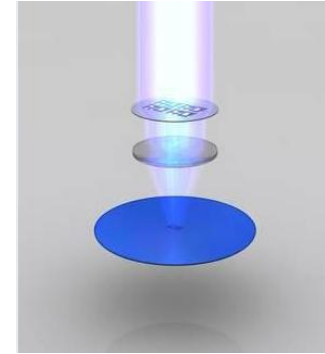
From sand to application

Advanced integrated packaging
Authority in back-end assembly processes
Automation & integration of assembly process steps

Flyer – Semiconductor - Training (2day)

TRAINING CONTENT:

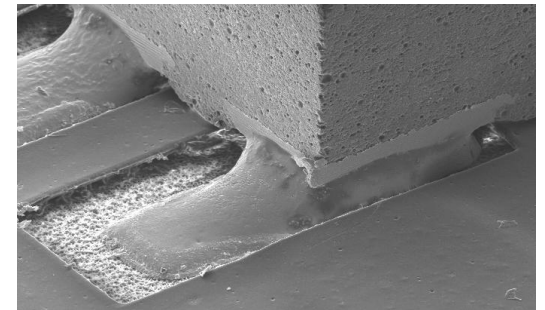
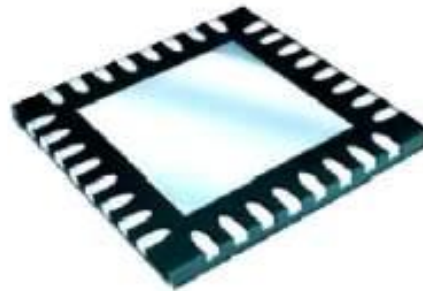
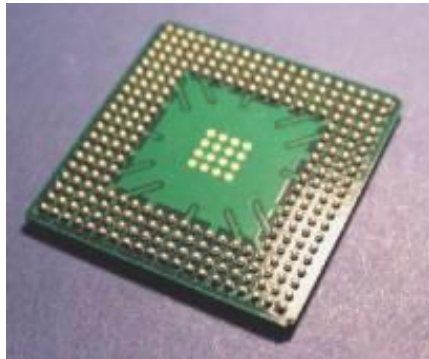
- Wafer fab. process steps and control plans
 - Process overview and trends
 - What is a wafer fab. and how is a design transferred into a product
- Workshop wafer fab. related 8D report.



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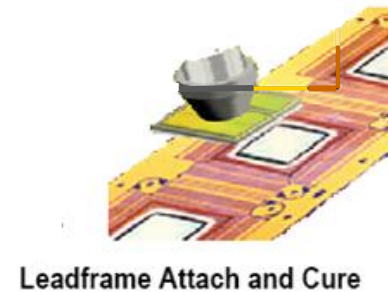
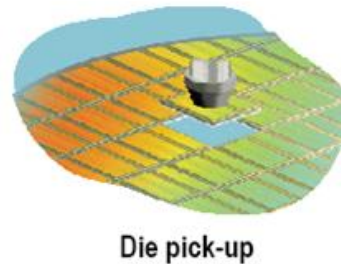
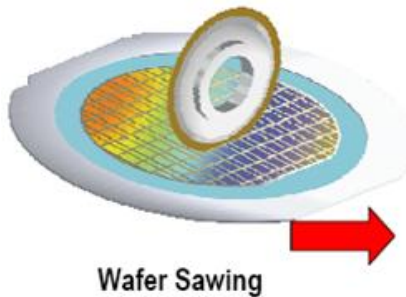
- Introduction in packaging
 - Package concepts
 - Bill Of Material
 - Qualification & reliability
 - PC Board interconnect/mounting (Leaded, leadless products e.g. QFN)



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TRAINING CONTENT:

- Back-end assembly
 - Assembly process flow
 - Failure modes
 - Control plans and Out-of Control Action Plans (OCAP)
 - Standard and non standard test methods



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TRAINING CONTENT:

- Packing and transport
 - ESD sensitivity and prevention
 - Product transport sensitivity and risks
- Workshop back-end related 8D reports.

